

LNJ03004GLD1

Surface Mounting Chip LED

3230 Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	860	mW
Forward current *1	I_F	120	mA
Pulse forward current *2	I_{FP}	200	mA
Junction temperature	T_j	110	$^\circ\text{C}$
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *1: I_F is different by radiated factor of evaluation board.

This value is mounted on evaluation board at $R_{thj-a} = 25.0^\circ\text{C/W}$.

*2: The condition of pulse current I_{FP} is 55 ms pulse width, 10 % duty.

■ Lighting Color

- White

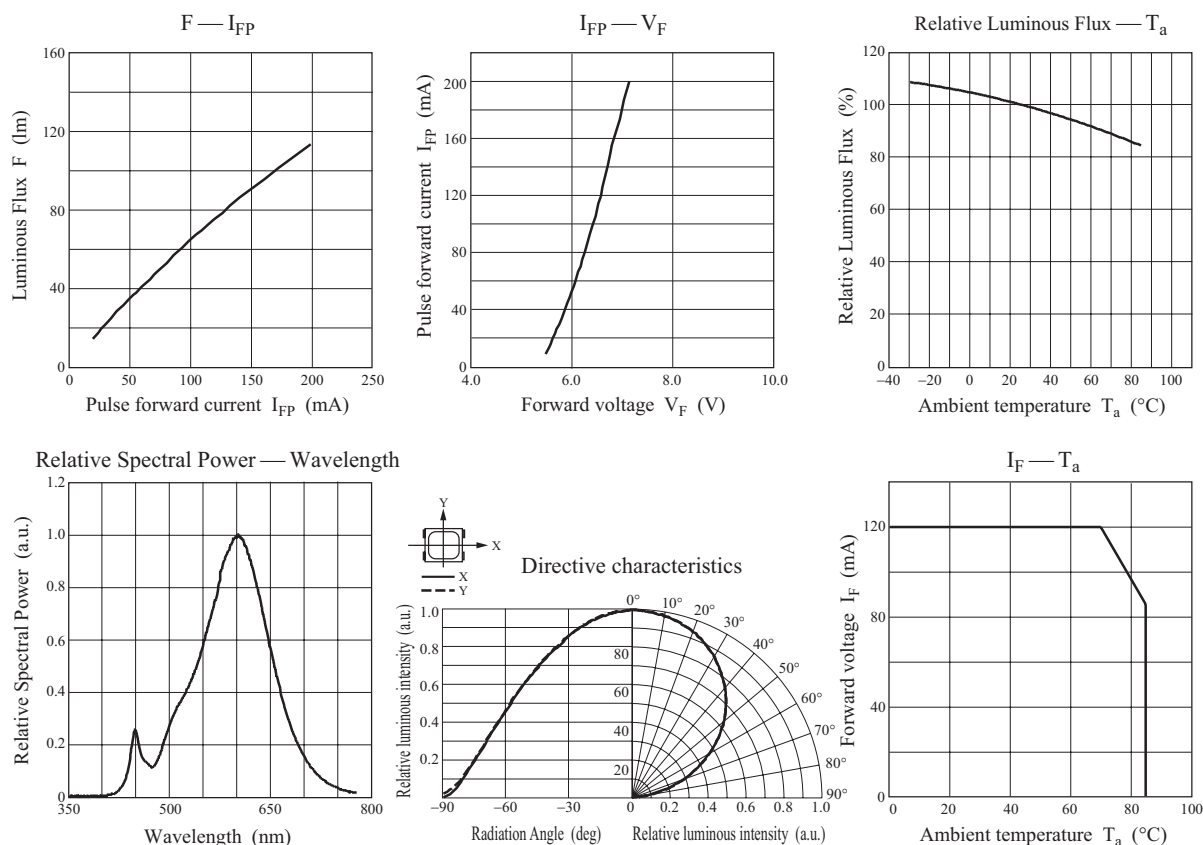
■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage *1	V_F	$I_{FP} = 75\text{ mA}$	5.7	6.2	6.7	V
Luminous flux *2	F	$I_{FP} = 75\text{ mA}$	37.0	50.0	66.0	lm
Chromaticity coordinates *3	x	$I_{FP} = 75\text{ mA}$		0.459		—
	y	$I_{FP} = 75\text{ mA}$		0.412		—
Color Rendering Index	Ra	$I_{FP} = 75\text{ mA}$		82		—

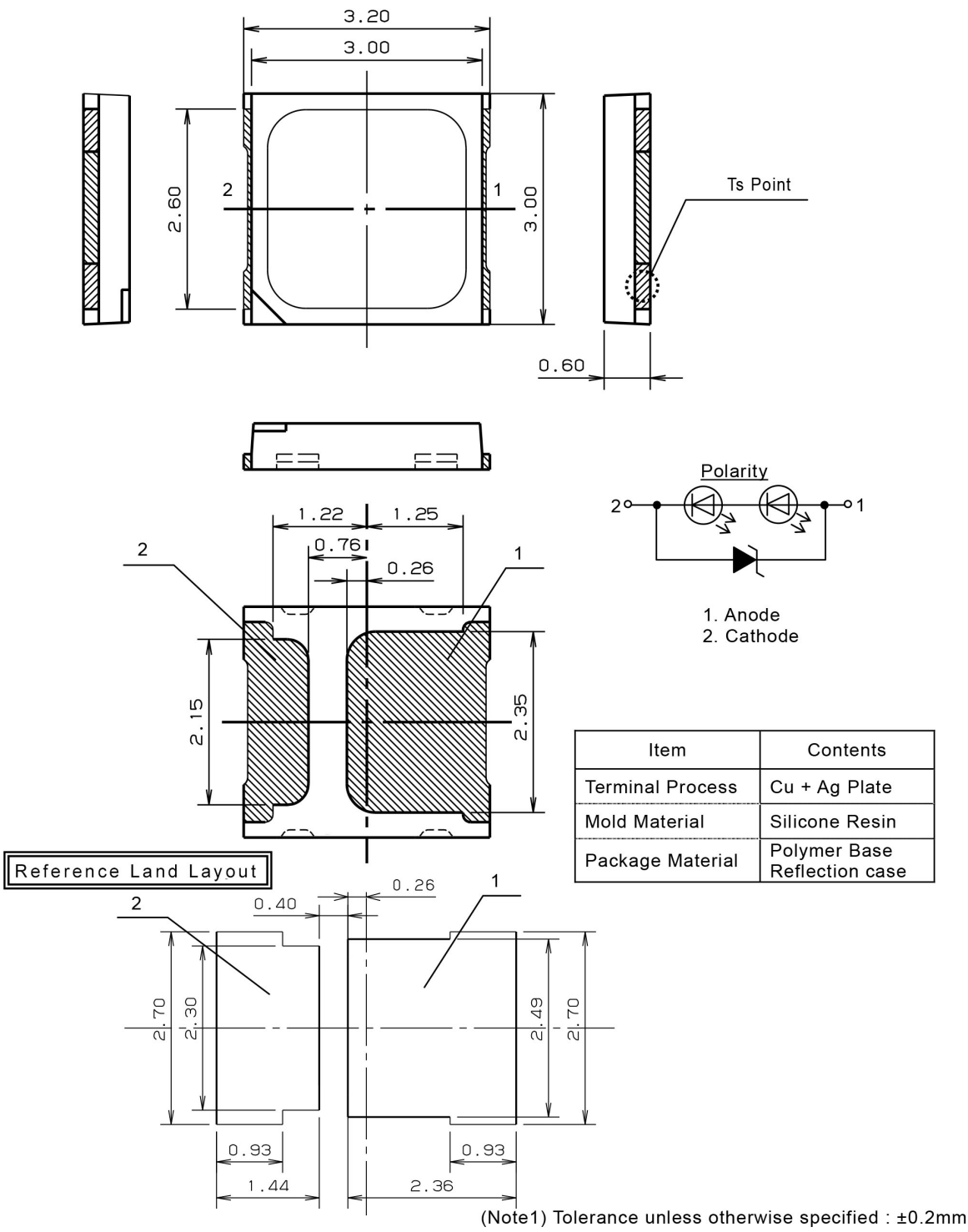
Note) *1: Complete Forward Voltage measurement within 0.1 seconds. Tolerance $\pm 3\%$

*2: Complete Luminous flux measurement within 0.1 seconds. Tolerance $\pm 10\%$

*3: Complete Chromaticity coordinates measurement within 0.1 seconds. Tolerance of chromaticity is ± 0.01



■ Package (Unit: mm)



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